



**samtec**

# COMPANY OVERVIEW

INNOVATIVE TECHNOLOGIES • SUDDEN SERVICE • GLOBAL REACH



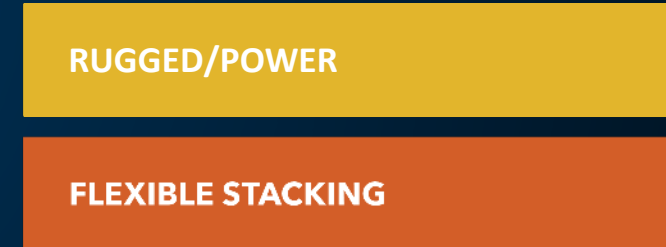


# BUSINESS MODEL

## SILICON-TO-SILICON



## CORE BOARD-TO-BOARD



## SUDDEN SERVICE



## GLOBAL INFRASTRUCTURE





# GLOBAL SUPPORT NETWORK

With more than **25,000+** direct customers spanning all industries, Samtec **serves** well-known **global tech giants**,

**small start-ups**, and **everyone** in between.



Samtec Confidential

**13** DESIGN CENTERS

**14** OPERATION FACILITIES

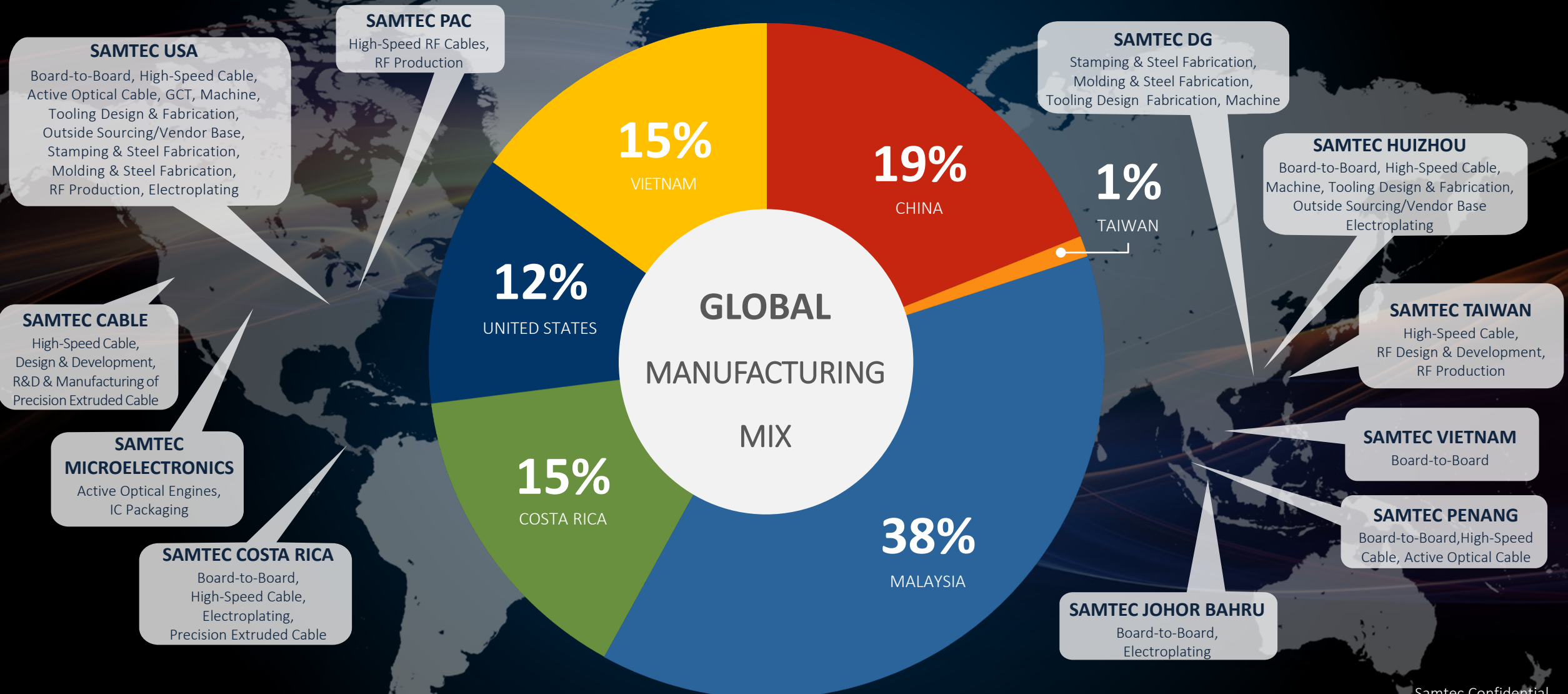
**24** SALES OFFICES

**125+** SALES SUPPORT

**6.5K+** GLOBAL EMPLOYEES



# UNMATCHED GLOBAL SERVICE



# MARKETS SERVED | PERCENT OF SALES

Based on 2023 Sales



INDUSTRIAL

22%



COMPUTER/  
SEMICONDUCTOR

22%



DATAKOM

13%



MEDICAL

13%



INSTRUMENTATION

9%



AERO/  
DEFENSE

11%



AUTO/TRANS/  
TELEMATICS

7%



CONSUMER

3%

Customer Base of 50,000

25,000 (Direct) + 25,000 (Digital)



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# INTEGRATION LEADS TO INNOVATION

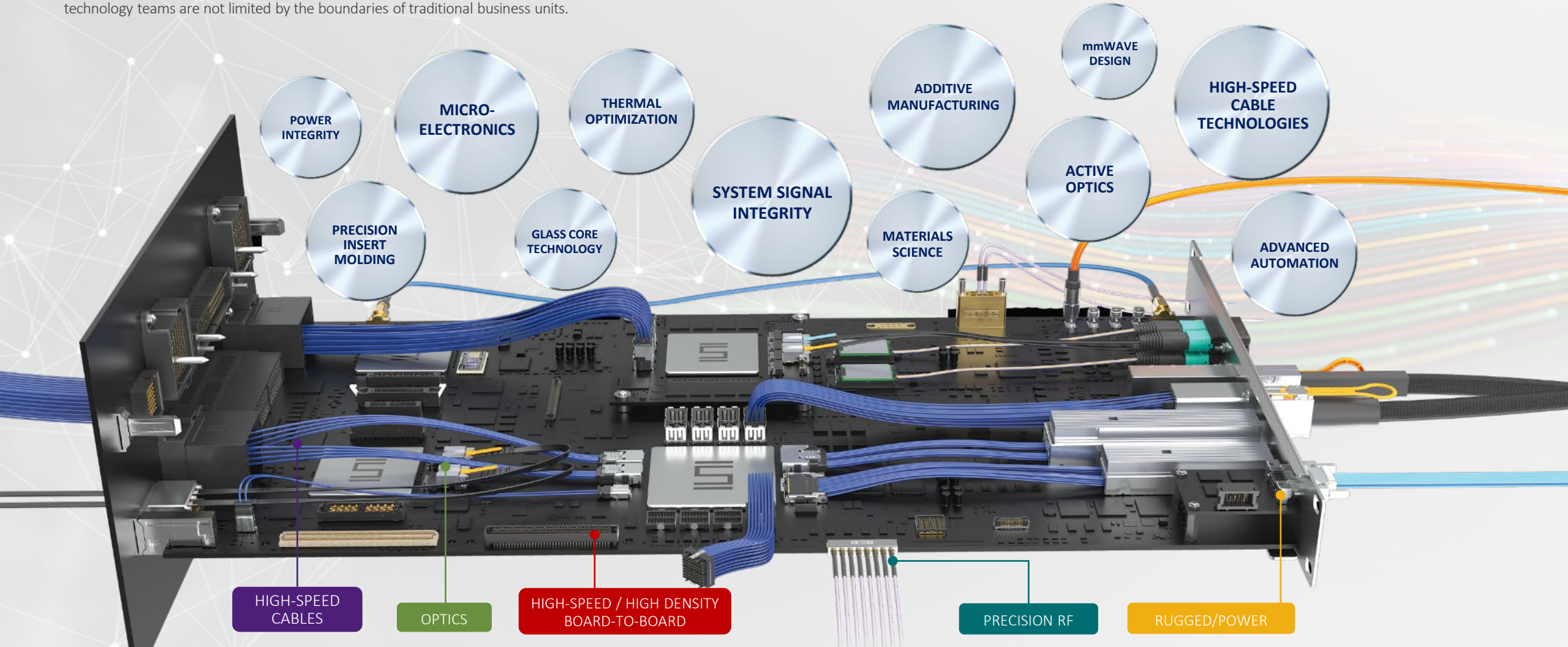
Samtec's integrated approach provides high-level design and development of advanced interconnect systems and TECHNOLOGIES, along with industry-leading expertise that allows us to offer effective strategies and support for optimizing the entire signal channel of high-performance systems.

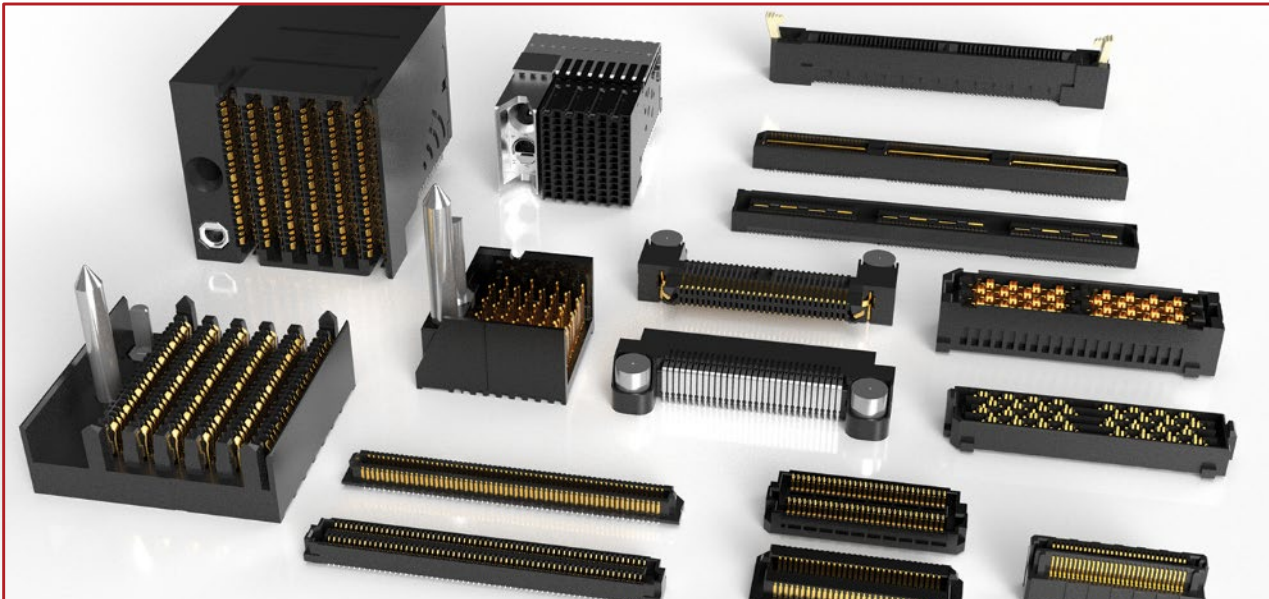
Samtec is structured like no other company in the interconnect industry. We work in a fully integrated capacity that enables true collaboration and results in uniquely innovative PRODUCTS because our technology teams are not limited by the boundaries of traditional business units.

# SILICON-TO-SILICON SOLUTIONS

As bandwidth, scale and power requirements continue to challenge conventional engineering methods, we want to help optimize the landscape of your entire system – and develop solutions, together.

Samtec's industry-leading signal integrity expertise, full system optimization strategies and, innovative products and technologies help address the challenges of next gen data transmission for a path to 224 Gbps and beyond.





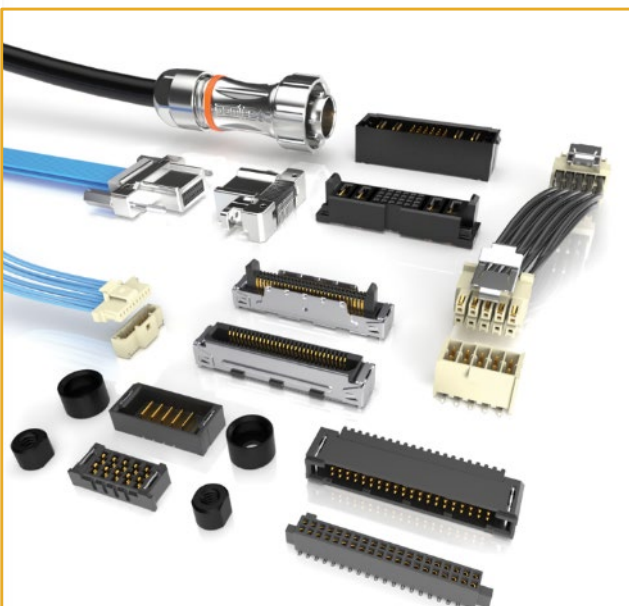
## HIGH-SPEED BOARD-TO-BOARD

OPEN-PIN-FIELD ARRAYS | GROUND PLANE STRIPS | ULTRA-MICRO | BACKPLANE



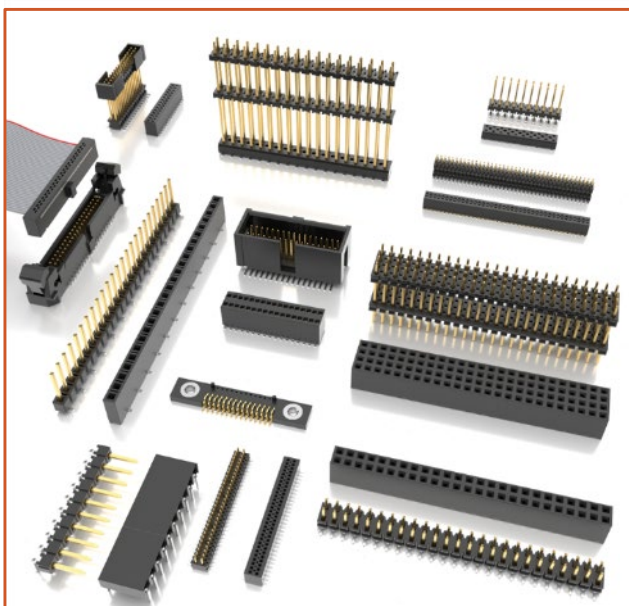
## HIGH-SPEED CABLE

FLYOVER® | MID-BOARD & PANEL | BACKPLANE | MICRO COAX & TWINAX



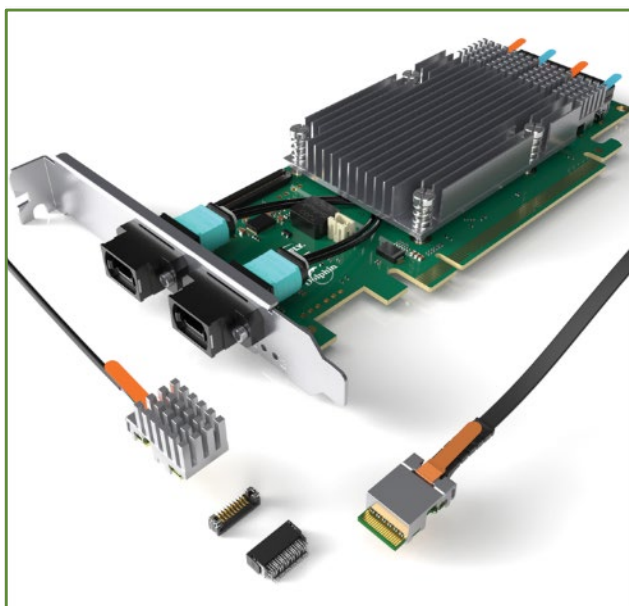
## RUGGED/POWER

RUGGED BOARD-TO-BOARD | BLADE POWER  
MICRO DISCRETE WIRE | RUGGED I/O | ULTRA RUGGED



## FLEXIBLE STACKING

LOW PROFILE | PASS-THROUGH | ONE-PIECE  
SKYSCRAPERS | SHROUDED HEADERS | IDC SYSTEMS



## OPTICS

MICRO FLYOVER SYSTEMS™ | EXTENDED TEMP  
PCI EXPRESS®-OVER-FIBER



## RF

PRECISION RF | 50 Ω SOLUTIONS  
75 Ω SOLUTIONS | ORIGINAL SOLUTIONS



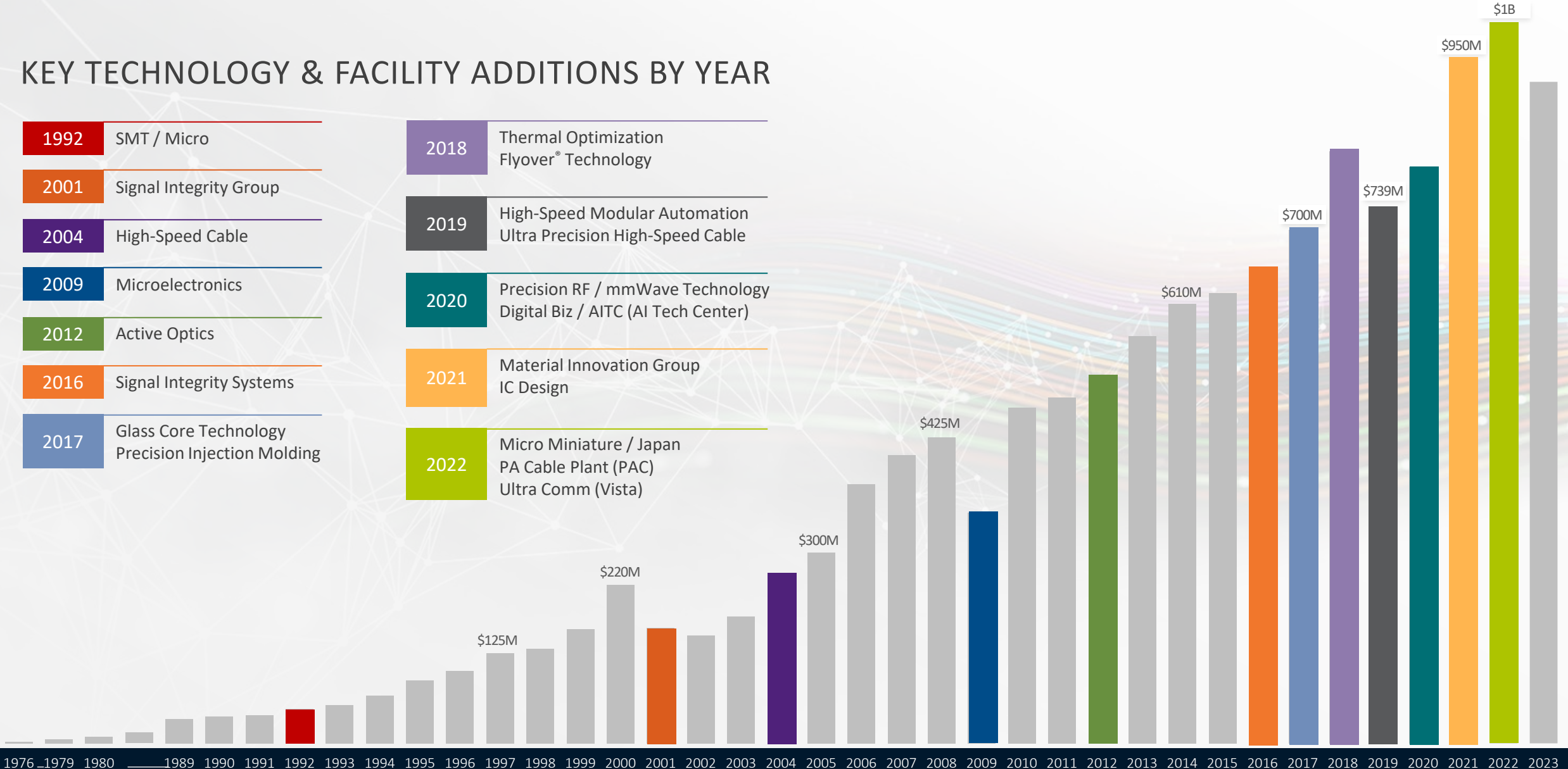


# SALES GROWTH & TECHNOLOGY EVOLUTION

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## KEY TECHNOLOGY & FACILITY ADDITIONS BY YEAR

|      |  |      |   |
|------|--|------|---|
| 1992 | SMT / Micro  | 2018 | Thermal Optimization<br>Flyover® Technology                             |
| 2001 | Signal Integrity Group                               | 2019 | High-Speed Modular Automation<br>Ultra Precision High-Speed Cable       |
| 2004 | High-Speed Cable                                     | 2020 | Precision RF / mmWave Technology<br>Digital Biz / AITC (AI Tech Center) |
| 2009 | Microelectronics                                     | 2021 | Material Innovation Group<br>IC Design                                  |
| 2012 | Active Optics  | 2022 | Micro Miniature / Japan<br>PA Cable Plant (PAC)<br>Ultra Comm (Vista)   |
| 2016 | Signal Integrity Systems                             |      |   |
| 2017 | Glass Core Technology<br>Precision Injection Molding |      |   |



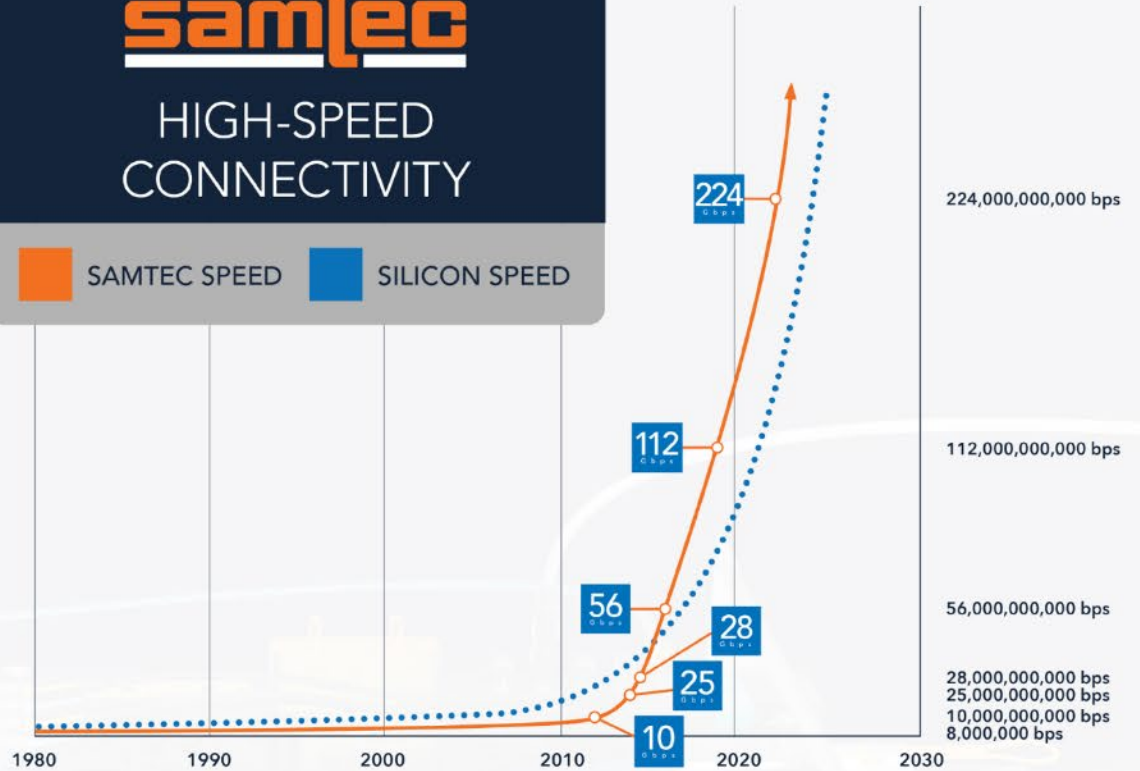
# THE TECHNICAL RENAISSANCE IS...

...driven by *progress*, challenged with unprecedented performance *demands*, a catalyst for next level technologies and *innovation*...



**samtec**  
HIGH-SPEED CONNECTIVITY

SAMTEC SPEED    SILICON SPEED



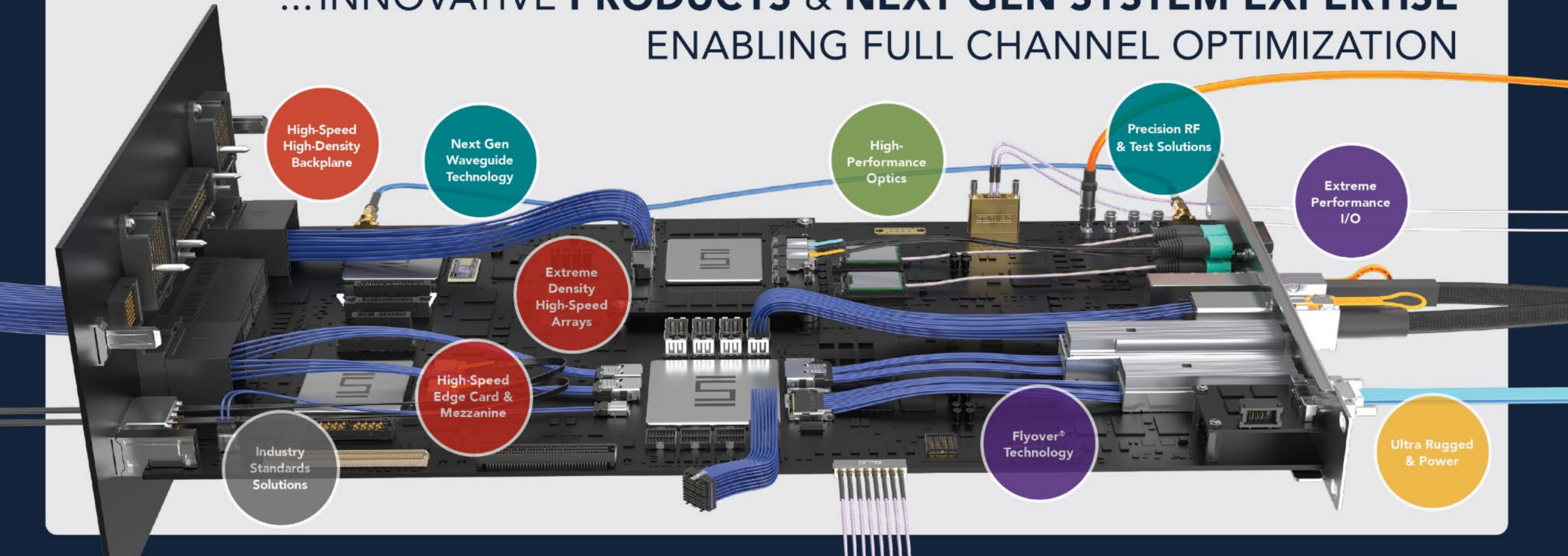
...and enabled by Samtec's

# SILICON-TO-SILICON<sup>TM</sup> SOLUTIONS

# SILICON-TO-SILICON™ CONNECTIVITY SOLUTIONS



...INNOVATIVE PRODUCTS & NEXT GEN SYSTEM EXPERTISE  
ENABLING FULL CHANNEL OPTIMIZATION



High-Speed  
High-Density  
Backplane

Next Gen  
Waveguide  
Technology

High-  
Performance  
Optics

Precision RF  
& Test Solutions

Extreme  
Performance  
I/O

Extreme  
Density  
High-Speed  
Arrays

High-Speed  
Edge Card &  
Mezzanine

Flyover®  
Technology

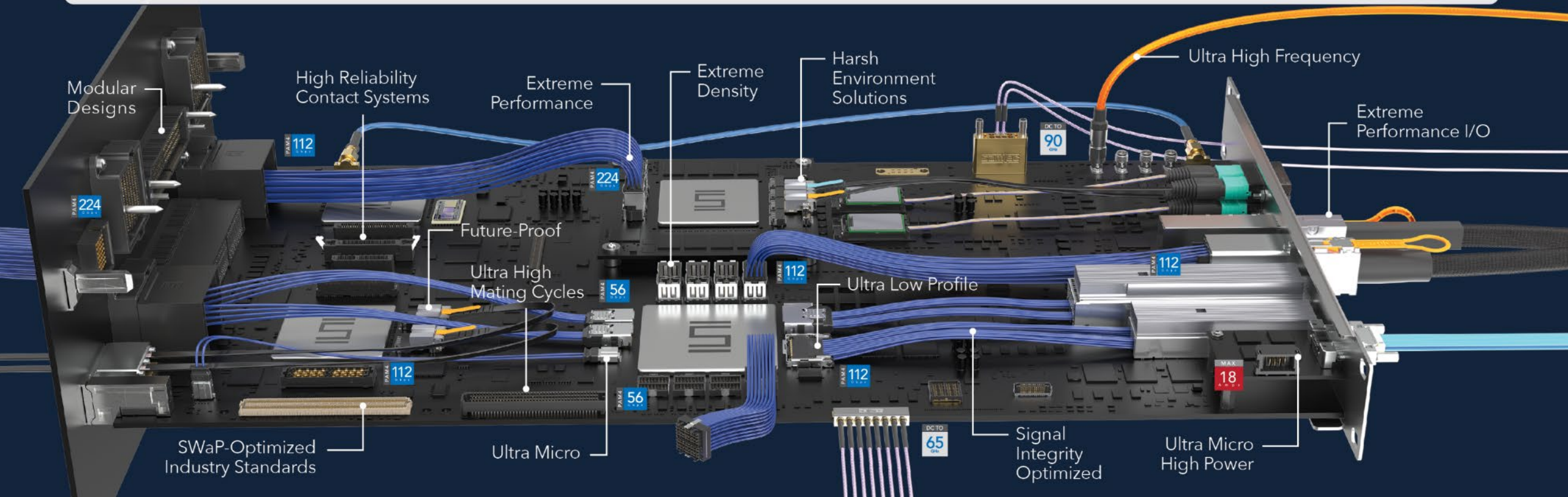
Ultra Rugged  
& Power

Industry  
Standards  
Solutions

# SILICON-TO-SILICON™ CONNECTIVITY SOLUTIONS



Samtec's **Silicon-to-Silicon™ Solutions** are high-performance interconnect systems and technologies that are engineered to **meet and exceed industry-standard demands**. These solutions, combined with high-level design assistance and technical expertise, uniquely position Samtec to help ensure **Full System Optimization, from Silicon-to-Silicon™** - and all points in between.





**samtec**

The logo features the word "samtec" in a bold, orange, sans-serif font. The letters are contained within a white rectangular frame consisting of two horizontal bars, one above and one below the text. The background is dark blue with abstract, glowing orange and white light trails.

SUDDEN SERVICE®